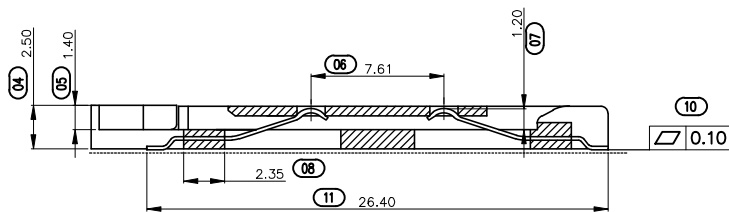
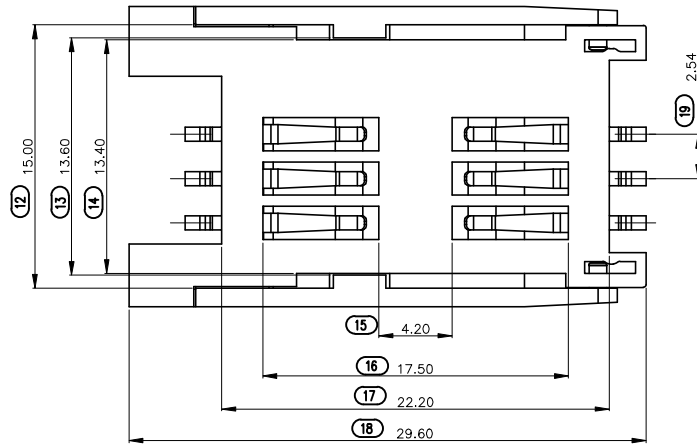
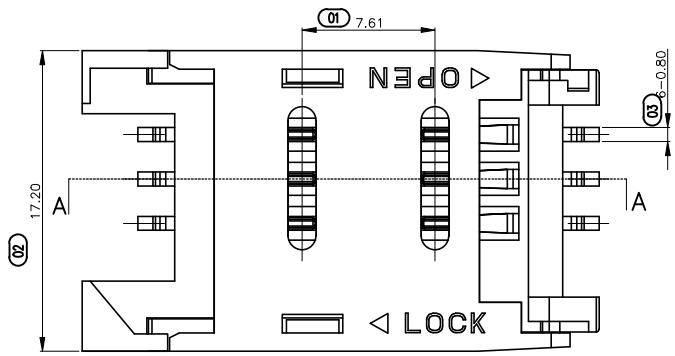
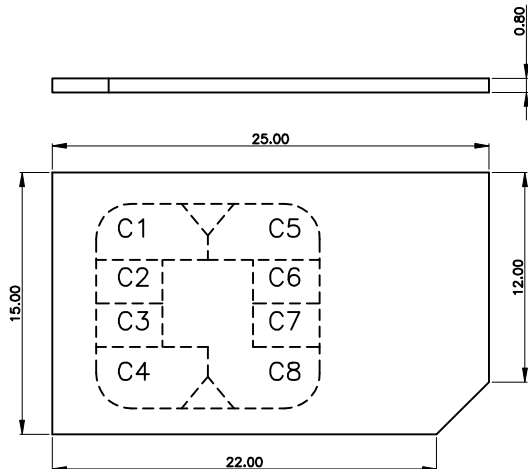




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SEC: A-A

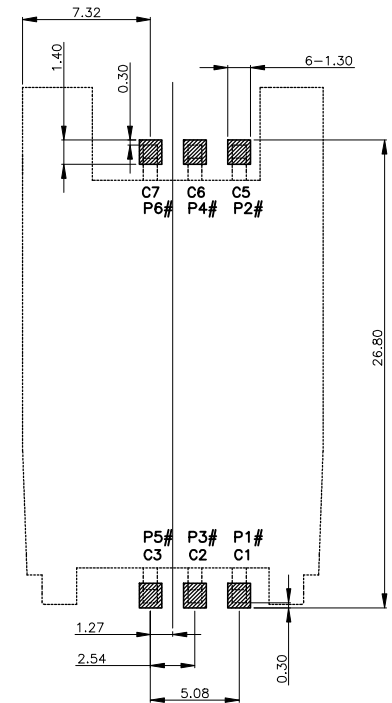


- A. Material:**
 1. Insulator: High temperature thermoplastic UL94V-0, (BLACK LCP)
 2. Pho. Bronze: Plating, 50U" MIN NICKEL UNDERPLATED; 3-8U" GOLD ON THE CONTACT AREA; 100U" TIN PLATING ON SOLDER TAIL
- B. Electrical specifications:**
 Voltage rating: 10 V AC
 Current rating: 0.5A
 Dielectric strength: 500V AC for 1 minute min
 Insulation resistance: 1000 M ohm
 Contact resistance: 100 mill.ohm max
 Operation temperature: -25°C to +95°C
 Product withstanding rff low soldering 260°C for 10s



SIM 示意图
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE: ±0.05)
RECOMMENDED METAL MASK T=0.12MM

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD		
DECIMALS:	ANGLES:	TITLE	2.5H 6PIN SIM CARD SMT.	
X : ±0.5	X : ±2°	DWN	xiong	SIM-211-P6
X.X : ±0.20	X.X : ±1°	CHKD	lee	SCALE: 1:1 UNIT: mm
X.XX : ±0.10		APVD	wang	SIZE: A4 SHEET: 10F 1 REV: A4
CUSTOMER COPY				